20/05/02
20020290056

162162

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau

(43) International Publication Date
31 May 2001 (31.05.2001)

PCT

(10) International Publication Number
WO 01/39563 A2

(51) International Patent Classification[7]: H05K 3/00

(21) International Application Number: PCT/US00/32211

(22) International Filing Date:
21 November 2000 (21.11.2000)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
09/447,112 22 November 1999 (22.11.1999) US

(71) Applicant: PPG INDUSTRIES OHIO, INC. [US/US]; 3800 West 143rd Street, Cleveland, OH 44111 (US).

(72) Inventors: EGLOFF, Debra, R.; 131 Village Drive, Cranberry, PA 16066 (US). FRY, Terry, E.; 5 Hollow Way, Sewickley, PA 15143 (US). NOVICH, Bruce, E.; 7 Starboard, Barrington, RI 02806 (US). SHEPARD, Paula, A.; 2606 Dogwood Court, Wexford, PA 15090 (US). WEBSTER, Stephen, P.; 629 St. James Street, Pittsburgh, PA 15232 (US).

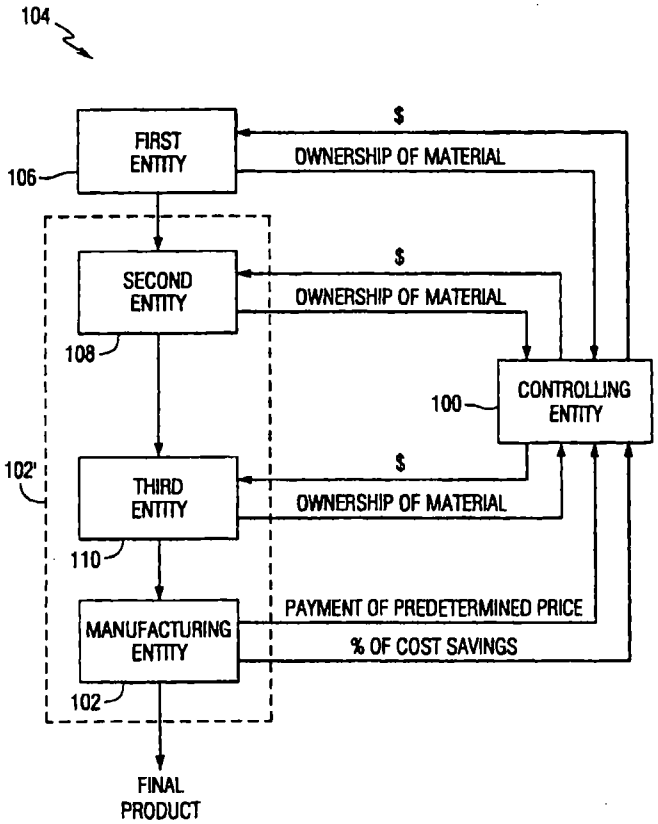
(74) Agents: SIMINERIO, Andrew, C. et al.; PPG Industries, Inc., One PPG Place, Intellectual Property Department, Pittsburgh, PA 15272 (US).

(81) Designated States *(national)*: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CR, CU, CZ, DE, DK, DM, DZ, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, TZ, UA, UG, UZ, VN, YU, ZA, ZW.

(84) Designated States *(regional)*: ARIPO patent (GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE,

[Continued on next page]

(54) Title: METHOD OF ALLOCATING COST SAVINGS ASSOCIATED WITH A MANUFACTURING PROCESS



(57) Abstract: The present invention also provides a method of cost savings feedback in a printed circuit board value chain that includes a yarn manufacturer which manufactures fiber glass yarn, a weaver which forms the fiber glass yarn into a fabric, a laminator which forms the fabric into laminate and a printed circuit board (PCB) manufacturer which forms the laminate into a PCB which the PCB manufacturer sells to an OEM customer, the method comprising the steps of (a) having a controlling entity; (b) transferring to the controlling entity at least partial control of fiber glass yarn manufactured by a yarn manufacturer; (c) causing the fiber glass yarn to be delivered to a weaver for weaving into fabric; (d) transferring to the controlling entity at least partial control of fabric formed by the weaver; (e) causing the fabric to be delivered to a laminator for laminating; (f) transferring to the controlling entity at least partial control of laminate formed by the laminator; (g) selling the laminate to a PCB manufacturer at a market price for other laminate formed from other fiber glass yarn; (h) causing the laminate to be delivered to the PCB manufacturer; (i) determining cost savings realized by the PCB manufacturer in response to forming PCBs utilizing the laminate versus utilizing the other laminate formed from the other fiber glass yarn; and (j) allocating at least a portion of the cost savings to the controlling entity.

WO 01/39563 A2

ACTION

IT, LU, MC, NL, PT, SE, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GW, ML, MR, NE, SN, TD, TG).

Published:

— *Without international search report and to be republished upon receipt of that report.*

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.